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HMC472A* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS 🖳

View a parametric search of comparable parts.

EVALUATION KITS

• HMC472ALP4 Evaluation Board

DOCUMENTATION

Data Sheet

· HMC472A Data Sheet

TOOLS AND SIMULATIONS

• HMC472A S-parameters

REFERENCE MATERIALS 🖵

Quality Documentation

- Package/Assembly Qualification Test Report: LP4, LP4B, LP4C, LP4K (QTR: 2013-00487 REV: 04)
- Semiconductor Qualification Test Report: PHEMT-J (QTR: 2013-00285)

DESIGN RESOURCES 🖵

- HMC472A Material Declaration
- PCN-PDN Information
- · Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all HMC472A EngineerZone Discussions.

SAMPLE AND BUY

Visit the product page to see pricing options.

TECHNICAL SUPPORT

Submit a technical question or find your regional support number.

DOCUMENT FEEDBACK \Box

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0.5 dB LSB Steps to 31.5 dB Single Control Line Per Bit

TTL/CMOS Compatible Control

± 0.25 dB Typical Step Error

Single +5V Supply

Features

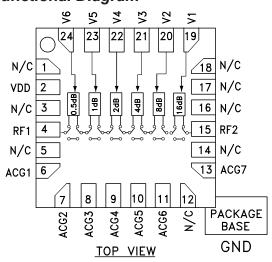
Typical Applications

The HMC472ALP4E is ideal for:

- 3G Infrastructure & access points
- Cellular/3G, LTE & UMB
- WiMAX, WiBN & Fixed Wireless
- Test Equipment and Sensors
- GSM, WCDMA & TD-SCDMA

24 Lead Ceramic 4x4mm SMT Package: 16mm²

Functional Diagram



General Description

The HMC472ALP4E are broadband 6-bit GaAs IC digital attenuators in low cost leadless surface mount packages. This single positive control line per bit digital attenuator incorporates off chip AC ground capacitors for near DC operation, making it suitable for a wide variety of RF and IF applications. Covering DC to 3.8 GHz, the insertion loss is less than 2.0 dB typical. The attenuator bit values are 0.5 (LSB), 1, 2, 4, 8, and 16 dB for a total attenuation of 31.5 dB. Attenuation accuracy is excellent at ± 0.25 dB typical step error with an IIP3 of +54 dBm. Six TTL/CMOS control inputs are used to select each attenuation state. A single Vdd bias of +5V is required.

Electrical Specifications,

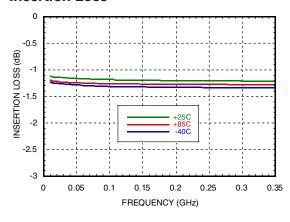
 $T_A = +25^{\circ}$ C, With Vdd = +5V & VctI = 0/+5V (Unless Otherwise Noted)

Parameter	Frequency (GHz)	Min.	Тур.	Max.	Units	
Insertion Loss		DC - 1.5 GHz 1.5 - 3.0 GHz 3.0 - 3.8 GHz		1.4 1.7 1.9	1.8 2.3 3	dB dB dB
Attenuation Range		DC - 3.8 GHz		31.5		dB
Return Loss (RF1 & RF2, All Atten. States)	DC - 3.8 GHz		20		dB	
Attenuation Accuracy: (Referenced to Insertion Loss) All Attenuation States 0.5 - 3.5 dB States 4.0 - 31.5 dB States All Attenuation States All Attenuation States		DC - 1.0 GHz 1.0 - 2.2 GHz 1.0 - 2.2 GHz 2.2 - 3.0 GHz 3.0 - 3.8 GHz	± (0.25 + ± (0.15 + ± (0.30 +	3% of Atten. S 3% of Atten. So 4% of Atten. So 3% of Atten. So 5% of Atten. So	etting) Max. etting) Max. etting) Max	dB dB dB dB dB
Input Power for 0.1 dB Compression		0.1 - 3.8 GHz		30		dBm
Input Third Order Intercept Point (Two-Tone Input Power= 0 dBm Each Tone)	REF - 15.5 dB States 16.0 - 31.5 dB States	0.1 - 3.8 GHz		54 49		dBm dBm
Switching Characteristics tRISE, tFALL (10/90% RF) tON, tOFF (50% CTL to 10/90% RF)		DC - 3.8 GHz		40 60		ns ns

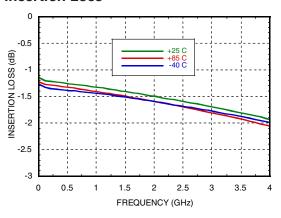




Insertion Loss

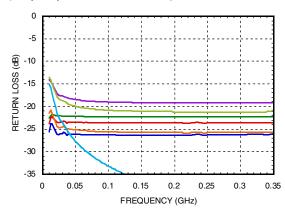


Insertion Loss



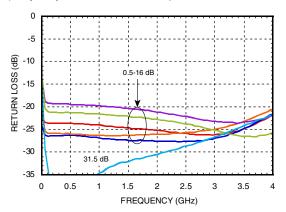
Return Loss RF1, RF2

(Only Major States are Shown)



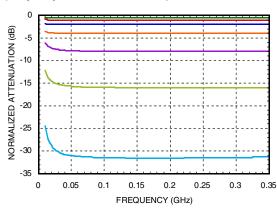
Return Loss RF1, RF2

(Only Major States are Shown)



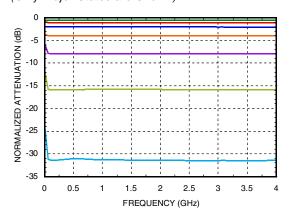
Normalized Attenuation

(Only Major States are Shown)



Normalized Attenuation

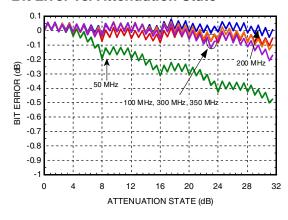
(Only Major States are Shown)



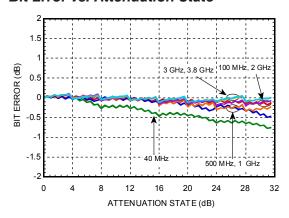




Bit Error vs. Attenuation State

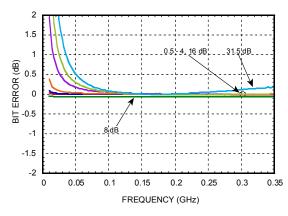


Bit Error vs. Attenuation State



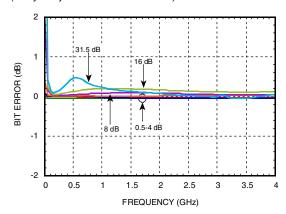
Bit Error vs. Frequency

(Only Major States are Shown)



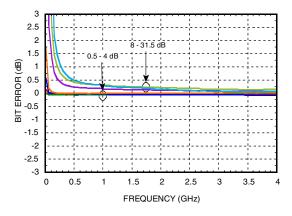
Bit Error vs. Frequency

(Only Major States are Shown)



Bit Error vs. Frequency without AC Ground Caps

(Only Major States are Shown)

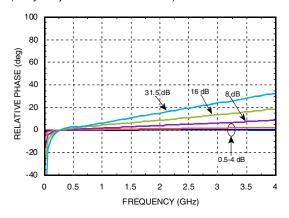




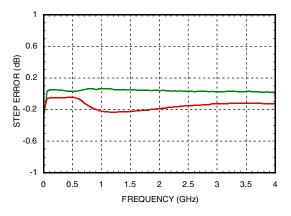


Relative Phase vs. Frequency

(Only Major States are Shown)



Worst Case Step Error Between Successive Attenuation States



Bias Voltage & Current

$Vdd = +5V \pm 10\%$			
Vdd (V)	ldd (Typ.) (mA)		
+4.5	2.4		
+5.0	2.5		
+5.5	2.6		

Control Voltage

State	Bias Condition
Low	0 to +0.8 Vdc @ -5 uA Typ.
High	+ 2.0 to + 5.0 Vdc @ 40 uA Typ.
Note: Vdd = +5V	

Truth Table

Control Voltage Input						Attenuation	
V1 16 dB	V2 8 dB	V3 4 dB	V4 2 dB	V5 1 dB	V6 0.5 dB	State RF1 - RF2	
High	High	High	High	High	High	Reference I.L.	
High	High	High	High	High	Low	0.5 dB	
High	High	High	High	Low	High	1 dB	
High	High	High	Low	High	High	2 dB	
High	High	Low	High	High	High	4 dB	
High	Low	High	High	High	High	8 dB	
Low	High	High	High	High	High	16 dB	
Low	Low	Low	Low	Low	Low	31.5 dB	

Any combination of the above states will provide an attenuation approximately equal to the sum of the bits selected.



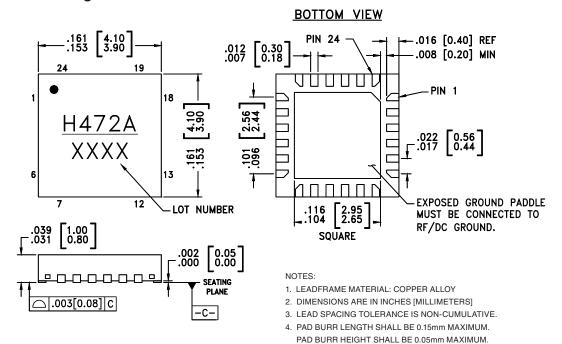


Absolute Maximum Ratings

RF Input Power (DC - 3 GHz)	+28 dBm (T = +85 °C)	
Control Voltage Range (V1 to V6)	-1V to Vdd +1V	
Bias Voltage (Vdd)	+7V	
Channel Temperature	150 °C	
Continuous Pdiss (T = 85 °C) (derate 8.6 mW/°C above 85 °C)	0.56 W	
Thermal Resistance	116 °C/W	
Storage Temperature	-65 to +150 °C	
Operating Temperature	-40 to +85 °C	
ESD Sensitivity (HBM)	Class 1A	



Outline Drawing



Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [2]
HMC472ALP4E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [1]	<u>H472A</u> XXXX

5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.6. ALL GROUND LEADS AND GROUND PADDLE MUST BE

7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED

SOLDERED TO PCB RF GROUND.

LAND PATTERN.

[1] Max peak reflow temperature of 260 °C

[2] 4-Digit lot number XXXX





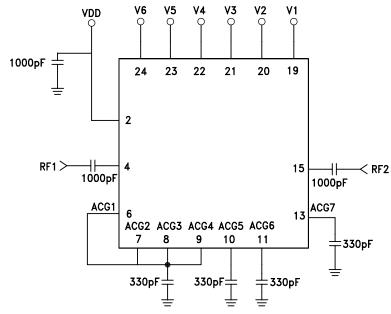
Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1, 3, 5, 12, 14, 16, 17, 18	N/C	These pins should be connected to PCB RF ground to maximize performance.	
2	Vdd	Supply Voltage.	
4, 15	RF1, RF2	This pin is DC coupled and matched to 50 Ohm. Blocking capacitors are required. Select value based on lowest frequency of operation.	RF1, O
6 - 11, 13	ACG1 - ACG7	External capacitors to ground are recommended for low and high frequency operation. Select value for lowest frequency of operation. Place capacitor as close to pins as possible. For operation from 700 to 2700 MHz, these pins may be left unconnected.	
19 - 24	V1 - V6	See truth table and control voltage table.	V1-V5 142K 500 =
	GND	Package bottom has an exposed metal paddle that must also be connected to RF/DC Ground.	GND =





Application Circuit

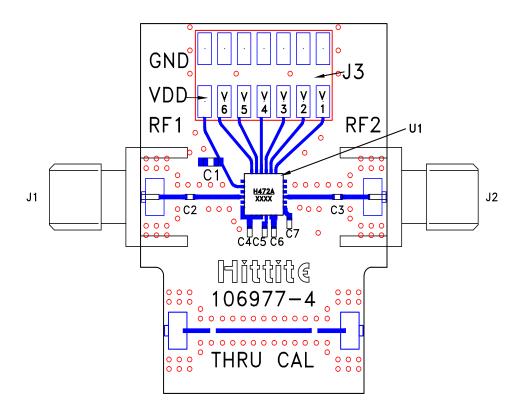


Note: For operations from 700 to 2700 MHz, pins 6 through 13 may be left unconnected.





Evaluation PCB



List of Materials for Evaluation PCB 107010 - HMC472ALP4 [1]

Item	Description	
J1 - J2	PCB Mount SMA Connector	
J3	14 Pin DC Connector	
C1	1000 pF Capacitor, 0603 Pkg.	
C2, C3	1000 pF Capacitor, 0402 Pkg.	
C4 - C7	330 pF Capacitor, 0402 Pkg.	
U1	HMC472ALP4E Digital Attenuator	
PCB [2]	106977 Evaluation PCB	

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.